

PRODUCT NO.
73725

PRODUCT NUMBER CODE

73725-X X X X LF

HOUSING COLOR OPTION
0-WHITE
1-BLACK

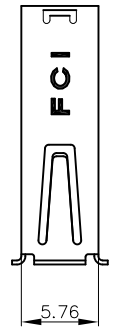
SENSOR CONTACT OPTION
0-WITH SENSOR CONTACT
1-WITHOUT SENSOR CONTACT

SHIELD PLATING OPTION
1- 1.25μm MINIMUM NICKEL UNDERPLATE &
2.5μm MINIMUM BRIGHT TIN OVER ALL AREA.
(HOLD DOWN STYLE "A")
2- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL;
2.5 μm MINIMUM MATTE TIN PLATED ON
HOLD DOWN AREA ONLY.(HOLD DOWN STYLE "B")
3- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL;
2.5 μm MINIMUM MATTE TIN PLATED ON
HOLD DOWN AREA ONLY.(HOLD DOWN STYLE "A")
4- 1.25μm MINIMUM NICKEL UNDERPLATED &
2.5μm MINIMUM BRIGHT TIN OVER ALL AREA.
(HOLD DOWN STYLE "B")
5- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL;
2.5μm MINIMUM MATTE TIN PLATED ON
HOLD DOWN AREA ONLY (HOLD DOWN STYLE "C")
6- 1.25μm MINIMUM NICKEL ONLY.
(HOLD DOWN STYLE "A")
7- 1.25μm MINIMUM NICKEL UNDERPLATED &
2.5 μm MINIMUM MATTE TIN PLATED OVER ALL.
(HOLD DOWN STYLE "A")
8- 1.25μm MINIMUM NICKEL UNDERPLATED &
2.5 μm MINIMUM MATTE TIN PLATED ALL AREA.
(HOLD DOWN STYLE "B")
9- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL;
2.5 μm MINIMUM MATTE TIN PLATED ON
HOLD DOWN AREA ONLY (HOLD DOWN STYLE "D")
S- 1.25μm MINIMUM NICKEL ONLY.(HOLD DOWN STYLE "A").
HIGH PERFORMANCE MATERIAL
FOR 12,000 DURABILITY CYCLES
A- 1.25μm MINIMUM NICKEL PLATED OVER ALL
2.5 μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY
(HOLD DOWN STYLE "F")
B- 1.25μm MINIMUM NICKEL PLATED OVER ALL
2.5 μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY
(HOLD DOWN STYLE "F")

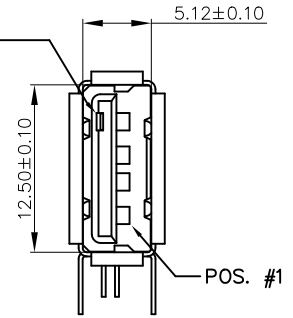
TERMINAL OPTION
50u" NI UNDERPLATE; 30u" GXT CONTACT AREA,100u" TIN TAIL AREA;
0- DIM "A": 2.29 (TERMINAL TAIL LENGTH);
1- DIM "A": 3.71 (TERMINAL TAIL LENGTH);

LEAD FREE OPTION
SEE NOTE 9

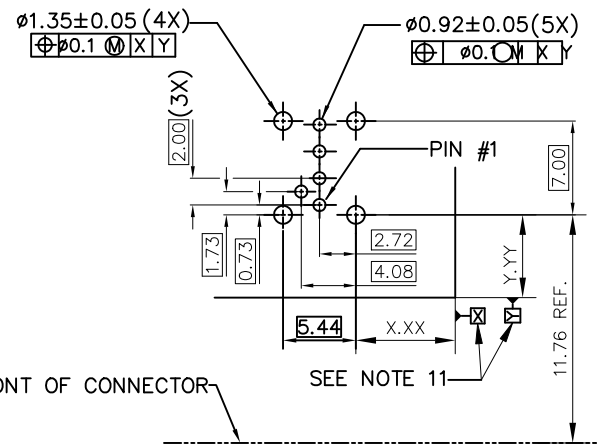
PACKAGING OPTION
B - TUBE
R - TAPE&REEL



SENSOR CONTACT

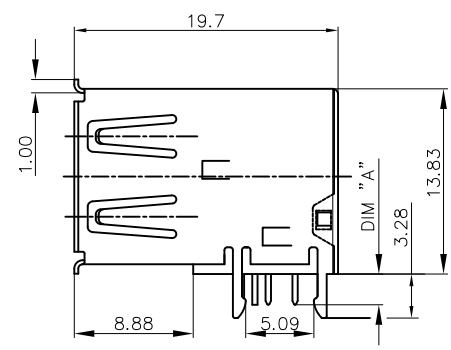


WITH SENSOR CONTACT



FRONT OF CONNECTOR

PC BOARD MOUNTING DIMENSIONS FOR 5 PIN



FOR 73725-X0X0B
HOLD DOWN STYLE "A"

NOTES:

- MATERIAL:
CONTACTS: COPPER ALLOY
SHIELD: COPPER ALLOY
HOUSING: UL 94V-0 THERMOPLASTIC, COLOR: SEE PRODUCT CODE
- PLATING:
CONTACTS: GOLD FLASH OVER PALLADIUM NICKEL (0.76μm MINIMUM)
IN CONTACT AREA; 2.5 μm TIN MINIMUM IN SOLDER TAIL AREA.
1.27 μm MINIMUM NICKEL UNDERPLATE OVER ALL SURFACES.
SHIELD: SEE PRODUCT NUMBER CODE.
(THE PLATING MEASURE POINT ON THE SHIELD HOLD DOWN AREA ONLY).
- DATUMS & BASIC DIMENSIONS TO BE DETERMINED BY CUSTOMER
- RECOMMENDED PCB BOARD THICKNESS IS 1.00 ~ 1.60mm EXCEPT 73725-1191BLF;
73725-1191BLF CAN BE USED FOR THE PCB BOARD THICKNESS 2.30 ~ 2.65mm.
- MAXIMUM PANEL THICKNESS TO BE 2.67mm IF MOUNTED BEHIND PANEL
- METAL SHELL SLIVER 0.20 MAX.
- NI PLATING DOES NOT COMPLY WITH THE USB STANDARDS
(TO BE CONTINUED)

mat'l. code				surface ¹²³ /tolerance		projection		product family				
				ISO 1302 ✓ ISO 406 ISO 1101				HPL 511 USB 2.0				
ltr	ecn no	dr	date	tolerances unless otherwise specified				title				
AJ	ELX-N-27706	LZ	2017/08/15	angles		mm		USB UP-RIGHT RECEPT				
				linear								
AD	ELX-N-012006	A.ZH	06/25/2012	0°±2°		scale 1:1						
AE	ELX-N-13463	A.ZH	11/14/2012	dr	PAMP	5/20/97	Amphenol FCI	dwg no		sheet 1 of 4	size	
AF	ELX-N-14592	J.HAN	06/10/2013	engr	R Y LIU	5/20/97		73725		A3		
AG	ELX-N-21594	LQ	08/04/2015	chr	R Y LIU	5/20/97						
AH	ELX-N-21919	LQ	08/04/2015	appd	JENN TSAO	5/20/97		type Product Customer Drawing				
sheet		revision										
index		sheet										

PRODUCT NO.
73725

(CONTINUED)

8. P/N'S WITH SUFFIX "LF" ARE LEAD FREE P/N'S

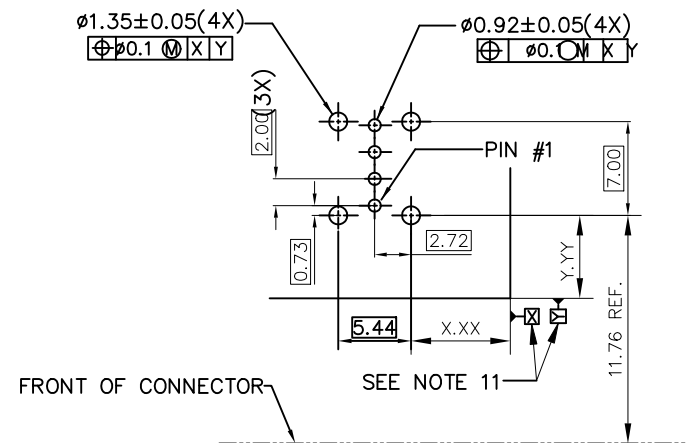
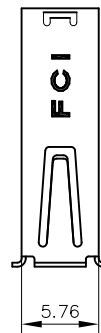
FOR LEAD FREE P/N, THE PRODUCT MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008

FOR THE PRODUCTS WITH THE METAL SHELL PLATING NICKEL AND MATTE SN CAN WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 40 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW PROCESS; FOR THE PRODUCTS WITH METAL SHELL PLATING BRIGHT SN OR SEMI-BRIGHT SN CAN'T WITHSTAND REFLOW AND JUST CAN WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN WAVE SOLDERING PROCESS.

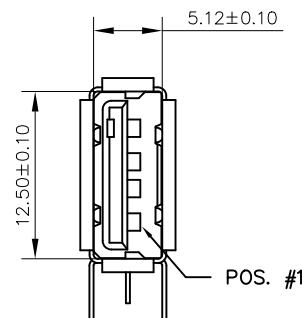
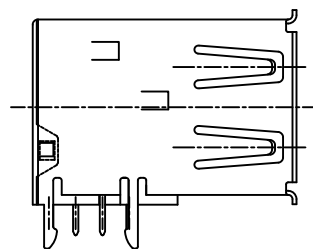
FOR ALL LEAD FREE P/N'S, WITH SUFFIX LF.

12. THE PRODUCT CAN BE USED FOR PIP PROCESS

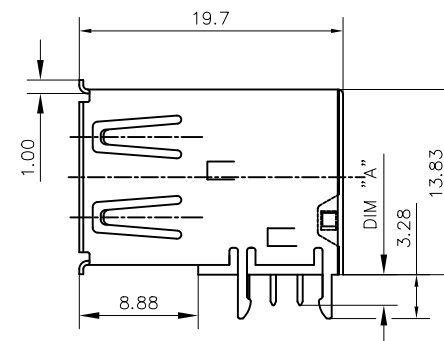
13. DATUM OF CUSTOMER'S PCB LAYOUT.



PC BOARD MOUNTING DIMENSIONS FOR 4 PIN

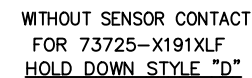
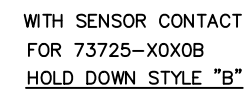
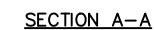
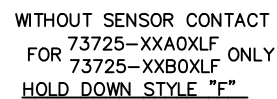
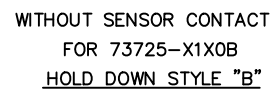


WITHOUT SENSOR CONTACT



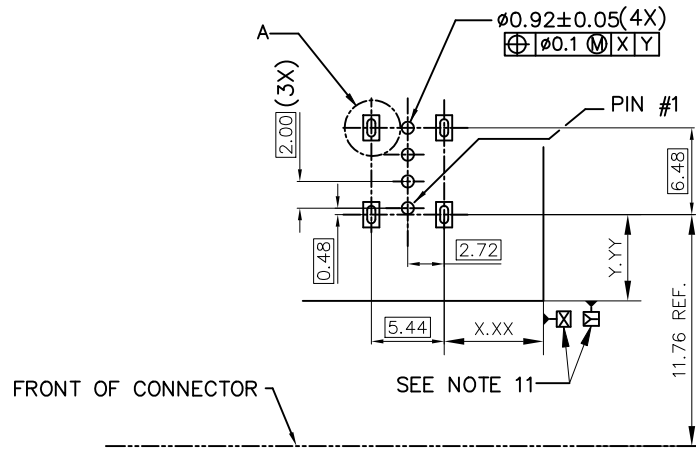
FOR 73725-X1X0B
HOLD DOWN STYLE "A"

mat'l. code				surface ¹²³ /tolerance			projection		product family			
				ISO 1302 ✓			ISO 406 ISO 1101		HPL 511 USB 2.0			
ltr	ecn	no	dr	date			tolerances unless otherwise specified		title			
AJ							mm		USB UP-RIGHT RECEPT			
				angles			.0±.30		dwg no sheet2 of 4 size			
				linear			.00±.20					
				0°±2'			.000±.10					
				dr			PAMP		5/20/97		Amphenol FCi	
				eng			R Y LIU		5/20/97		73725	
				chr			R Y LIU		5/20/97		A3	
				app			JENN TSAO		5/20/97		type Product Customer Drawing	
sheet		revision										
index		sheet										

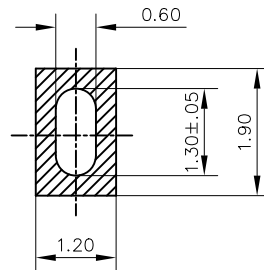


mat'l. code				surface ¹²³ /tolerance ISO 1302 ✓ ISO 406 ISO 1101			projection 		product family HPL 511 USB 2.0			
ltr	ecn no	dr	date	tolerances unless otherwise specified					title USB UP-RIGHT RECEPT			
AJ				angles linear			mm					
				0°±2'			scale 1:1					
				dr	PAMP	5/20/97	Amphenol FCi		dwg no		sheet3 of 4	size
				engr	R Y LIU	5/20/97			73725		A3	
				chr	R Y LIU	5/20/97						
				app'd	JENN TSAO	5/20/97						
sheet index		revision sheet										

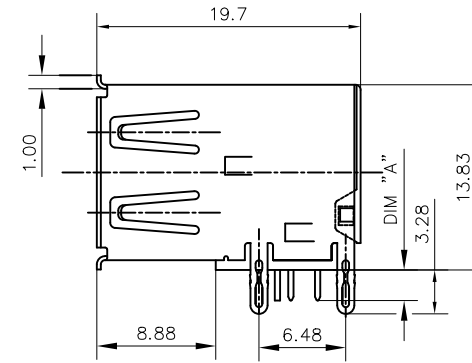
PRODUCT NO.
73725



PC BOARD MOUNTING DIMENSIONS FOR 4 PIN



DETAIL A 5 : 1



WITHOUT SENSOR CONTACT
FOR 73725-X150B
HOLD DOWN STYLE "C"

mat'l. code				surface ¹²³ /tolerance		projection		product family			
				ISO 1302 ✓ ISO 406 ISO 1101				HPL 511 USB 2.0			
ltr	ecn no	dr	date	tolerances unless otherwise specified				title			
AJ				angles	linear			USB UP-RIGHT RECEPT			
					.0±.30						
					.00±.20						
				0°±2°	.000±.10	scale 1:1					
				dr	PAMP	5/20/97	Amphenol FCI	dwg no		sheet 4 of 4	size
				engr	R Y LIU	5/20/97		73725		A3	
				chr	R Y LIU	5/20/97					
				appd	JENN TSAO	5/20/97					
sheet index		revision sheet									

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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